

# UTC UNISONIC TECHNOLOGIES CO., LTD

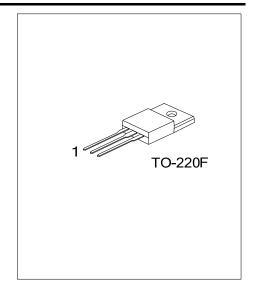
9N50 **Preliminary Power MOSFET** 

# 9A, 500V N-CHANNEL POWER MOSFET

#### **DESCRIPTION**

The UTC 9N50 is an N-channel mode power MOSFET using UTC's advanced technology to provide customers planar stripe and DMOS technology. This technology allows a minimum on-state resistance, superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

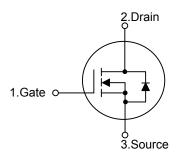
The UTC 9N50 is generally applied in high efficiency switch mode power supplies, active power factor correction and electronic lamp ballasts based on half bridge topology.



#### **FEATURES**

- \*  $R_{DS(ON)}$ =0.85 $\Omega$  @  $V_{GS}$ =10V
- \* High Switching Speed
- \* Improved dv/dt Capability
- \* 100% Avalanche Tested

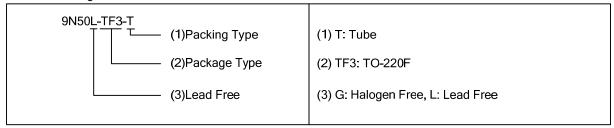
#### **SYMBOL**



#### ORDERING INFORMATION

	Ordering	Daakasa	Pin	Dooking				
ĺ	Lead Free	Halogen Free	Package	1	2	3	Packing	
ĺ	9N50L-TF3-T	9N50G-TF3-T	TO-220F	G	D	S	Tube	

Note: Pin Assignment: G: Gate D: Drain S: Source



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## ■ ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub>=25°C, unless otherwise noted)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	500	V
Gate-Source Voltage		$V_{GSS}$	±30	V
Drain Current	Continuous (T <sub>C</sub> =25°C)	I <sub>D</sub>	9 (Note 5)	Α
Diain Current	Pulsed (Note 2)	I <sub>DM</sub>	36 (Note 5)	Α
Avalanche Current (No	ote 2)	I <sub>AR</sub>	9	Α
Avalancha Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	360	mJ
Avalanche Energy	Repetitive (Note 4)	E <sub>AR</sub>	13.5	mJ
Peak Diode Recovery	dv/dt (Note 4)	dv/dt	4.5	V/ns
Power Dissipation		р	44	W
Derate above 25°C		P <sub>D</sub>	0.35	W/°C
Junction Temperature		TJ	+150	°C
Storage Temperature		T <sub>STG</sub>	-55~+150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature
- 3. L = 8mH,  $I_{AS}$  = 9A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C
- 4.  $I_{SD} \le 9A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$
- 5. Drain current limited by maximum junction temperature

#### ■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	$\theta_{JA}$	62.5	°C/W	
Junction to Case	$\theta_{JC}$	2.86	°C/W	

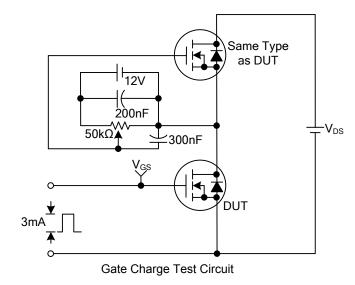
# ■ ELECTRICAL CHARACTERISTICS (T<sub>C</sub>=25°C, unless otherwise noted)

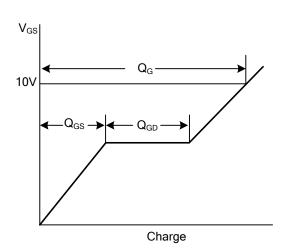
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V				V	
Drain-Source Leakage Current		I <sub>DSS</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V			1	•	
			V <sub>DS</sub> =400V, T <sub>C</sub> =125°C			10	μΑ	
Fc	orward	I <sub>GSS</sub>	$V_{GS}$ =+30V, $V_{DS}$ =0V			+100	nA	
Gate- Source Leakage Current Re	everse		V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V			-100	nA	
ON CHARACTERISTICS								
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_D=250\mu A$			4.0	V	
Static Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =4.5A		0.7	0.85	Ω	
DYNAMIC PARAMETERS								
Input Capacitance		$C_{ISS}$			790	1030	pF	
Output Capacitance Reverse Transfer Capacitance		Coss	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1.0MHz		130	170	pF	
		$C_{RSS}$			24	30	pF	
SWITCHING PARAMETERS								
otal Gate Charge		$Q_G$	V <sub>GS</sub> =10V, V <sub>DS</sub> =400V, I <sub>D</sub> =9A -(Note 1, 2)		28	35	nC	
Gate to Source Charge		$Q_GS$			4		nC	
Gate to Drain Charge		$Q_GD$			15		nC	
Turn-ON Delay Time		$t_{D(ON)}$	V <sub>DD</sub> =250V, I <sub>D</sub> =9A, R <sub>G</sub> =25Ω (Note 1, 2)		18	45	ns	
Rise Time		t <sub>R</sub>			65	140	ns	
Turn-OFF Delay Time		$t_{D(OFF)}$			93	195	ns	
Fall-Time		$t_{F}$			64	125	ns	
SOURCE- DRAIN DIODE RATING	S AND (	CHARACTERI	STICS					
Maximum Body-Diode Continuous (	Current	Is				9	Α	
Maximum Body-Diode Pulsed Current		I <sub>SM</sub>				36	Α	
Drain-Source Diode Forward Voltage		$V_{SD}$	I <sub>S</sub> =9A, V <sub>GS</sub> =0V			1.4	V	
Body Diode Reverse Recovery Time		t <sub>rr</sub>	I <sub>S</sub> =9A, V <sub>GS</sub> =0V, dI <sub>F</sub> /dt=100A/μs		335		ns	
Body Diode Reverse Recovery Charge		$Q_{RR}$	(Note 1)		2.95		μC	

Notes: 1. Pulse Test: Pulse width  $\leq 300 \mu s$ , Duty cycle  $\leq 2\%$ 

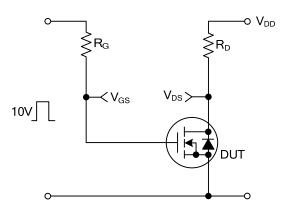
<sup>2.</sup> Essentially independent of operating temperature

## ■ TEST CIRCUITS AND WAVEFORMS

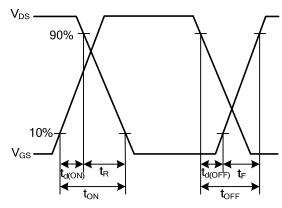




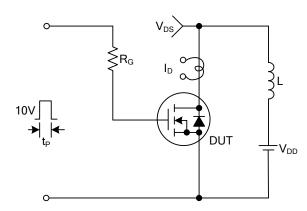
Gate Charge Waveforms



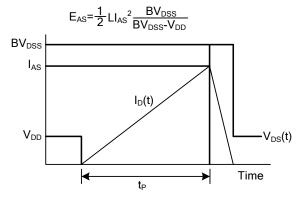
Resistive Switching Test Circuit



Resistive Switching Waveforms

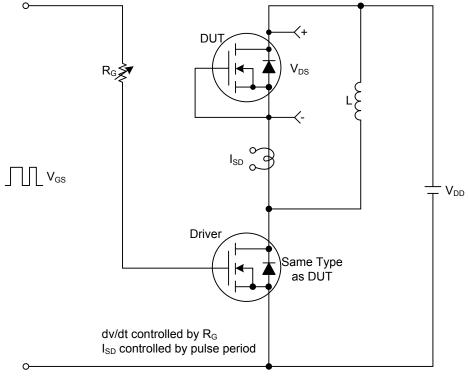


Unclamped Inductive Switching Test Circuit

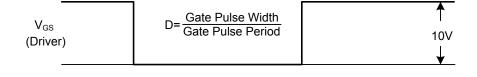


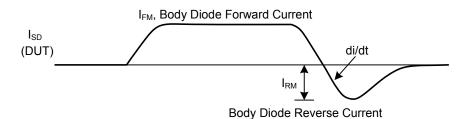
Unclamped Inductive Switching Waveforms

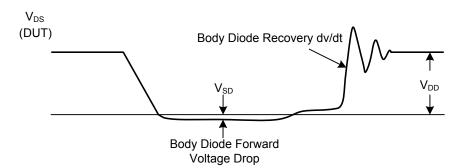
■ TEST CIRCUITS AND WAVEFORMS(Cont.)



Peak Diode Recovery dv/dt Test Circuit & Waveforms







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